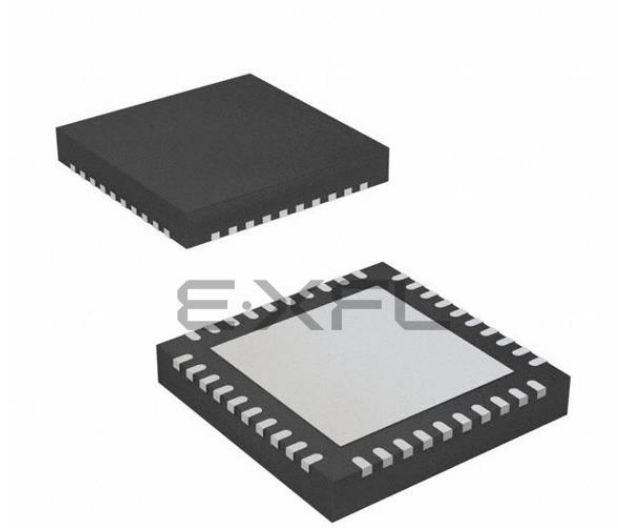

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	8051
Core Size	8-Bit
Speed	50MHz
Connectivity	EBI/EMI, SMBus (2-Wire/I²C), CANbus, LINbus, SPI, UART/USART
Peripherals	POR, PWM, Temp Sensor, WDT
Number of I/O	33
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4.25K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.25V
Data Converters	A/D 32x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	40-VFQFN Exposed Pad
Supplier Device Package	40-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f510-imr

List of Figures

Table 2.1. Product Selection Guide

Ordering Part Number	Flash Memory (kB)	CAN2.0B	LIN2.0	Digital Port I/Os	External Memory Interface	Package	Ordering Part Number	Flash Memory (kB)	CAN2.0B	LIN2.0	Digital Port I/Os	External Memory Interface	Package
C8051F500-IQ	64	✓	✓	40	✓	QFP-48	C8051F505-IQ	32	—	—	40	✓	QFP-48
C8051F500-IM	64	✓	✓	40	✓	QFN-48	C8051F505-IM	32	—	—	40	✓	QFN-48
C8051F501-IQ	64	—	—	40	✓	QFP-48	C8051F506-IQ	32	✓	✓	25	—	QFP-32
C8051F501-IM	64	—	—	40	✓	QFN-48	C8051F506-IM	32	✓	✓	25	—	QFN-32
C8051F502-IQ	64	✓	✓	25	—	QFP-32	C8051F507-IQ	32	—	—	25	—	QFP-32
C8051F502-IM	64	✓	✓	25	—	QFN-32	C8051F507-IM	32	—	—	25	—	QFN-32
C8051F503-IQ	64	—	—	25	—	QFP-32	C8051F508-IM	64	✓	✓	33	✓	QFN-40
C8051F503-IM	64	—	—	25	—	QFN-32	C8051F509-IM	64	—	—	33	✓	QFN-40
C8051F504-IQ	32	✓	✓	40	✓	QFP-48	C8051F510-IM	32	✓	✓	33	✓	QFN-40
C8051F504-IM	32	✓	✓	40	✓	QFN-48	C8051F511-IM	32	—	—	33	✓	QFN-40

Note: The suffix of the part number indicates the device rating and the package. All devices are RoHS compliant.

All of these devices are also available in an automotive version. For the automotive version, the -I in the ordering part number is replaced with -A. For example, the automotive version of the C8051F500-IM is the C8051F500-AM.

The -AM and -AQ devices receive full automotive quality production status, including AEC-Q100 qualification, registration with International Material Data System (IMDS) and Part Production Approval Process (PPAP) documentation. PPAP documentation is available at www.silabs.com with a registered and NDA approved user account. The -AM and -AQ devices enable high volume automotive OEM applications with their enhanced testing and processing. Please contact Silicon Labs sales for more information regarding –AM and -AQ devices for your automotive project.

Table 5.2. Global Electrical Characteristics (Continued)
–40 to +125 °C, 24 MHz system clock unless otherwise specified.

Parameter	Conditions	Min	Typ	Max	Units
Digital Supply Current—CPU Inactive (Idle Mode, not fetching instructions from Flash)					
I_{DD}[4]	V_{DD} = 2.1 V, F = 200 kHz	—	60	—	µA
	V_{DD} = 2.1 V, F = 1.5 MHz	—	460	—	µA
	V_{DD} = 2.1 V, F = 25 MHz	—	7.2	8.0	mA
	V_{DD} = 2.1 V, F = 50 MHz	—	14	16	mA
I_{DD}[4]	V_{DD} = 2.6 V, F = 200 kHz	—	75	—	µA
	V_{DD} = 2.6 V, F = 1.5 MHz	—	600	—	µA
	V_{DD} = 2.6 V, F = 25 MHz	—	9.3	15	mA
	V_{DD} = 2.6 V, F = 50 MHz	—	19	25	mA
I_{DD} Supply Sensitivity[4]	F = 25 MHz	—	57	—	%/V
	F = 1 MHz	—	56	—	
I_{DD} Frequency Sensitivity [4.6]	V_{DD} = 2.1V, F ≤ 12.5 MHz, T = 25 °C	—	0.29	—	mA/MHz
	V_{DD} = 2.1V, F > 12.5 MHz, T = 25 °C	—	0.29	—	
	V_{DD} = 2.6V, F ≤ 12.5 MHz, T = 25 °C	—	0.38	—	
	V_{DD} = 2.6V, F > 12.5 MHz, T = 25 °C	—	0.38	—	
Digital Supply Current[4] (Stop or Suspend Mode)	Oscillator not running, V_{DD} Monitor Disabled				µA
	Temp = 25 °C	—	2	—	
	Temp = 60 °C	—	10	—	
	Temp= 125 °C	—	120	—	

Notes:
1. Given in Table 5.4 on page 46.
2. V_{IO} should not be lower than the V_{DD} voltage.
3. SYSCLK must be at least 32 kHz to enable debugging.
4. Based on device characterization data; Not production tested. Does not include oscillator supply current.
5. IDD can be estimated for frequencies ≤ 12.5 MHz by simply multiplying the frequency of interest by the frequency sensitivity number for that range. When using these numbers to estimate I_{DD} for >12.5 MHz, the estimate should be the current at 50 MHz minus the difference in current indicated by the frequency sensitivity number. For example: V_{DD} = 2.6 V; F = 20 MHz, I_{DD} = 26 mA - (50 MHz - 20 MHz) * 0.48 mA/MHz = 11.6 mA.
6. Idle IDD can be estimated for frequencies ≤ 1 MHz by simply multiplying the frequency of interest by the frequency sensitivity number for that range. When using these numbers to estimate Idle I_{DD} for >1 MHz, the estimate should be the current at 50 MHz minus the difference in current indicated by the frequency sensitivity number.
   For example: V_{DD} = 2.6 V; F = 5 MHz, Idle I_{DD} = 21 mA – (50 MHz – 5 MHz) x 0.41 mA/MHz = 2.6 mA.

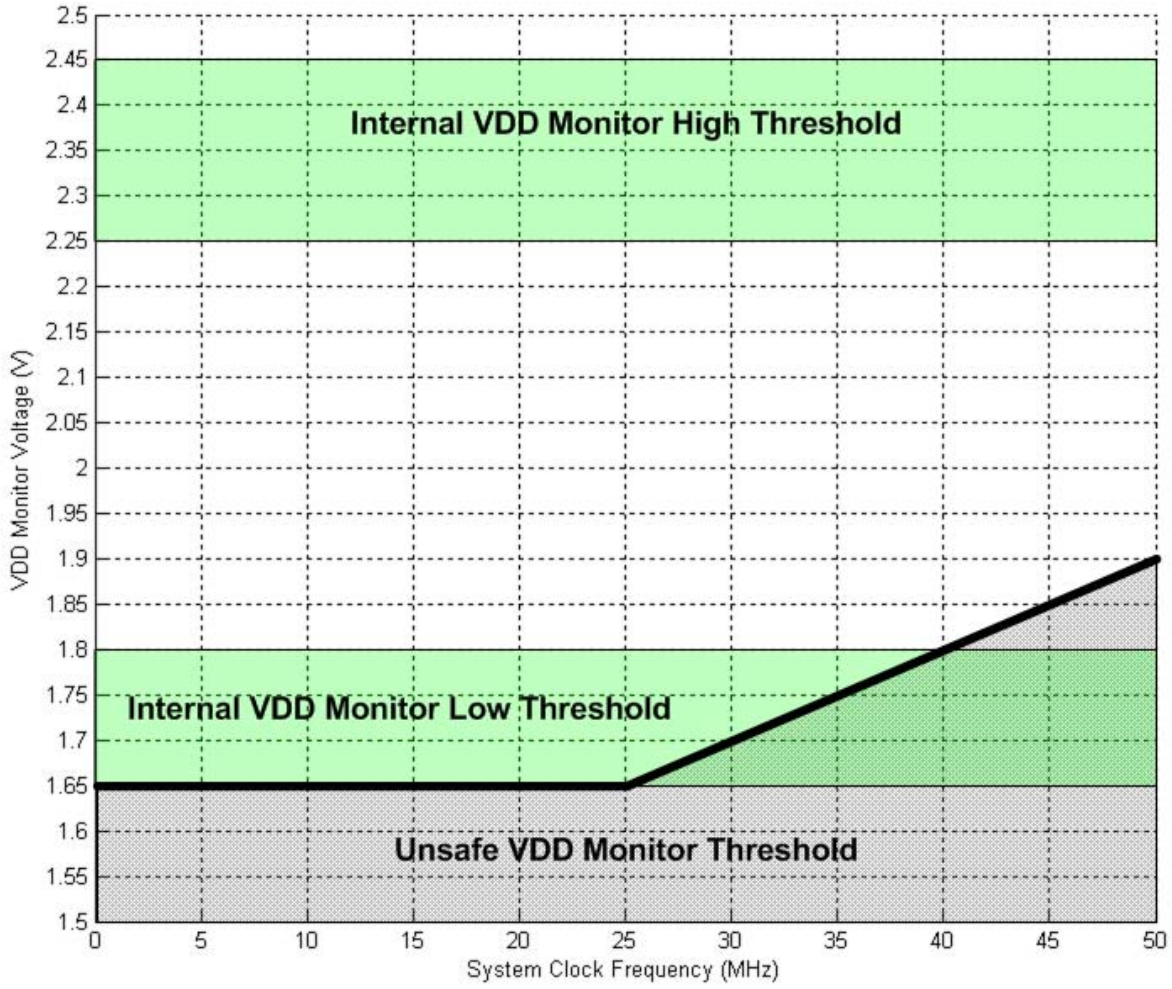


Figure 5.1. Minimum VDD Monitor Threshold vs. System Clock Frequency

Note: With system clock frequencies greater than 25 MHz, the VDD monitor level should be set to the high threshold (VDMLVL = 1b in SFR VDM0CN) to prevent undefined CPU operation. The high threshold should only be used with an external regulator powering VDD directly. See Figure 10.2 on page 85 for the recommended power supply connections.

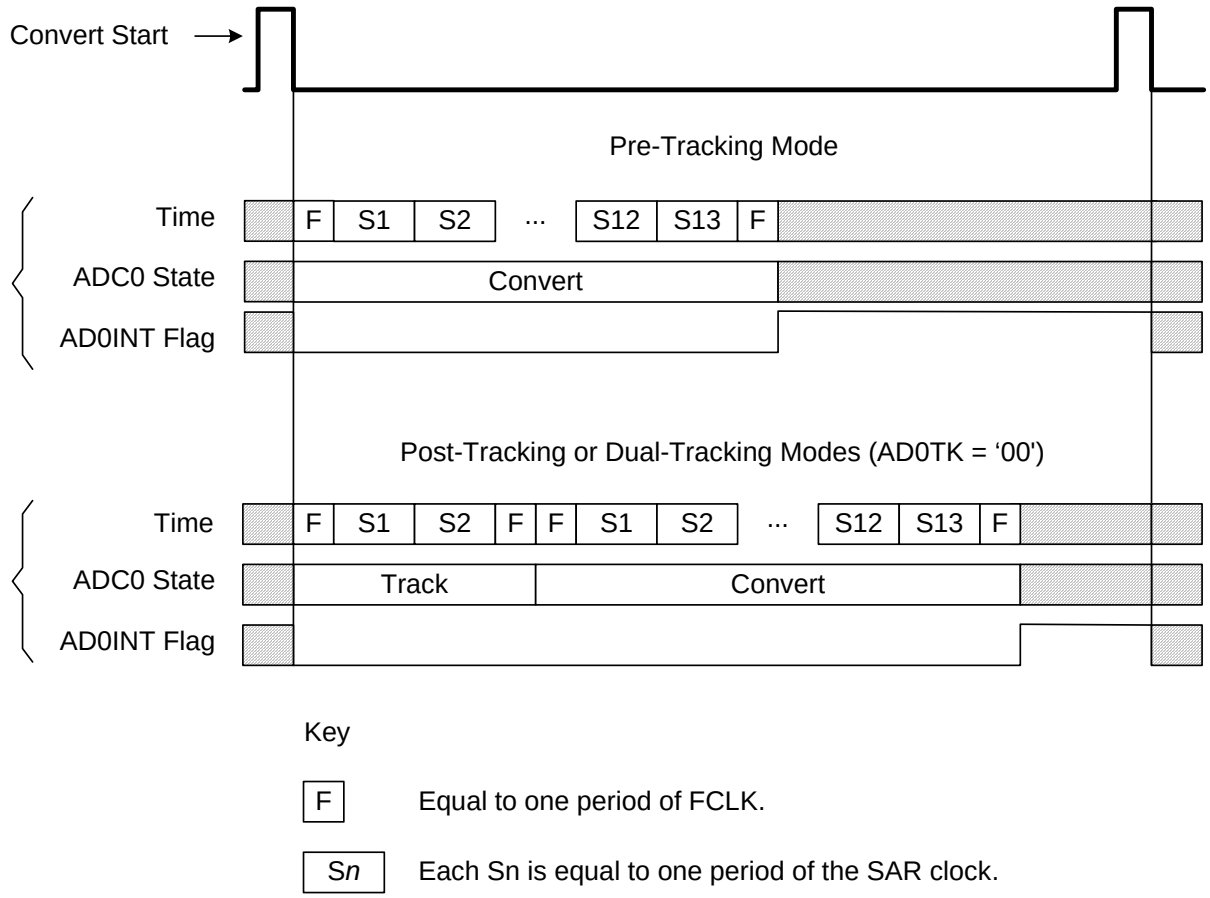


Figure 6.3. 12-Bit ADC Tracking Mode Example

6.1.4. Burst Mode

Burst Mode is a power saving feature that allows ADC0 to remain in a very low power state between conversions. When Burst Mode is enabled, ADC0 wakes from a very low power state, accumulates 1, 4, 8, or 16 samples using an internal Burst Mode clock (approximately 25 MHz), then re-enters a very low power state. Since the Burst Mode clock is independent of the system clock, ADC0 can perform multiple conversions then enter a very low power state within a single system clock cycle, even if the system clock is slow (e.g., 32.768 kHz), or suspended.

Burst Mode is enabled by setting BURSTEN to logic 1. When in Burst Mode, AD0EN controls the ADC0 idle power state (i.e. the state ADC0 enters when not tracking or performing conversions). If AD0EN is set to logic 0, ADC0 is powered down after each burst. If AD0EN is set to logic 1, ADC0 remains enabled after each burst. On each convert start signal, ADC0 is awakened from its Idle Power State. If ADC0 is powered down, it will automatically power up and wait the programmable Power-Up Time controlled by the AD0PWR bits. Otherwise, ADC0 will start tracking and converting immediately. Figure 6.4 shows an example of Burst Mode Operation with a slow system clock and a repeat count of 4.

Important Note: When Burst Mode is enabled, only Post-Tracking and Dual-Tracking modes can be used.

When Burst Mode is enabled, a single convert start will initiate a number of conversions equal to the repeat count. When Burst Mode is disabled, a convert start is required to initiate each conversion. In both modes, the ADC0 End of Conversion Interrupt Flag (AD0INT) will be set after “repeat count” conversions have

7. Temperature Sensor

An on-chip temperature sensor is included on the C8051F50x/F51x devices which can be directly accessed via the ADC multiplexer in single-ended configuration. To use the ADC to measure the temperature sensor, the ADC multiplexer channel should be configured to connect to the temperature sensor. The temperature sensor transfer function is shown in Figure 7.1. The output voltage (V_{TEMP}) is the positive ADC input is selected by bits AD0MX[4:0] in register ADC0MX. The TEMPE bit in register REF0CN enables/disables the temperature sensor, as described in SFR Definition 8.1. While disabled, the temperature sensor defaults to a high impedance state and any ADC measurements performed on the sensor will result in meaningless data. Refer to Table 5.10 for the slope and offset parameters of the temperature sensor.

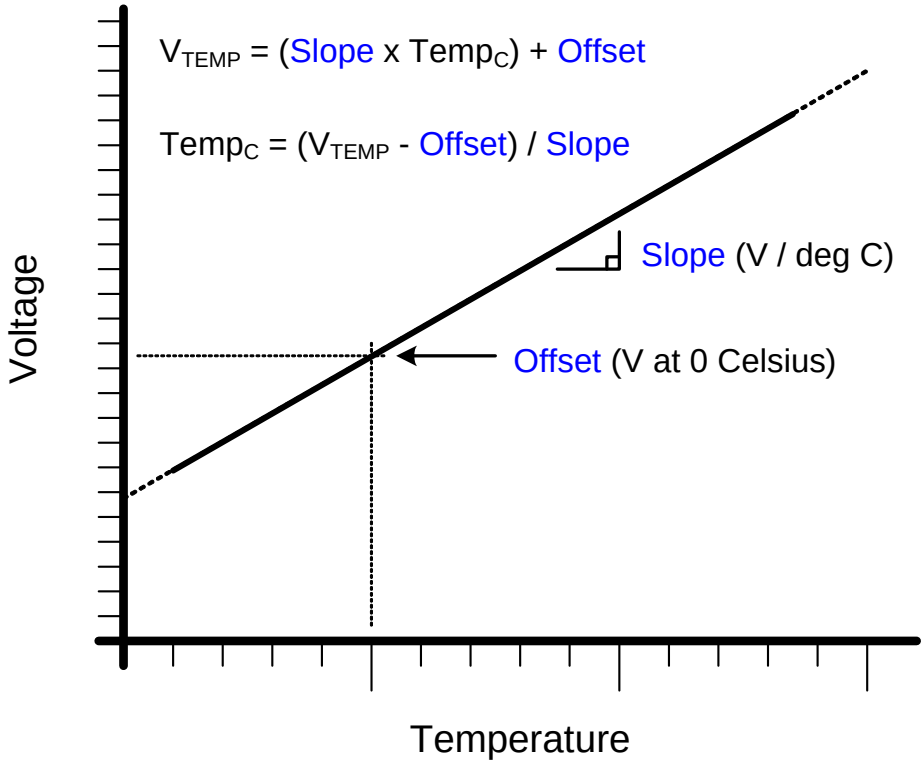


Figure 7.1. Temperature Sensor Transfer Function

10. Voltage Regulator (REG0)

C8051F50x/F51x devices include an on-chip low dropout voltage regulator (REG0). The input to REG0 at the V_{REGIN} pin can be as high as 5.25 V. The output can be selected by software to 2.1 V or 2.6 V. When enabled, the output of REG0 appears on the V_{DD} pin, powers the microcontroller core, and can be used to power external devices. On reset, REG0 is enabled and can be disabled by software.

The Voltage regulator can generate an interrupt (if enabled by EREG0, EIE2.0) that is triggered whenever the V_{REGIN} input voltage drops below the dropout threshold voltage. This dropout interrupt has no pending flag and the recommended procedure to use it is as follows:

1. Wait enough time to ensure the V_{REGIN} input voltage is stable
2. Enable the dropout interrupt (EREG0, EIE2.0) and select the proper priority (PREG0, EIP2.0)
3. If triggered, inside the interrupt disable it (clear EREG0, EIE2.0), execute all procedures necessary to protect your application (put it in a safe mode and leave the interrupt now disabled.
4. In the main application, now running in the safe mode, regularly checks the DROPOUT bit (REG0CN.0). Once it is cleared by the regulator hardware the application can enable the interrupt again (EREG0, EIE1.6) and return to the normal mode operation.

The input (V_{REGIN}) and output (V_{DD}) of the voltage regulator should both be bypassed with a large capacitor (4.7 µF + 0.1 µF) to ground as shown in Figure 10.1 below. This capacitor will eliminate power spikes and provide any immediate power required by the microcontroller. The settling time associated with the voltage regulator is shown in Table X.

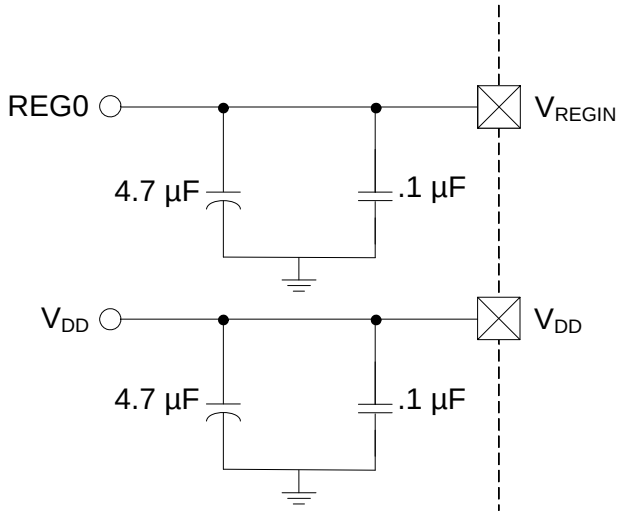


Figure 10.1. External Capacitors for Voltage Regulator Input/Output—Regulator Enabled

If the internal voltage regulator is not used, the V_{REGIN} input should be tied to V_{DD}, as shown in Figure 10.2.

18.4.2. Non-multiplexed Configuration

In Non-multiplexed mode, the Data Bus and the Address Bus pins are not shared. An example of a Non-multiplexed Configuration is shown in Figure 18.2. See Section “18.6.1. Non-Multiplexed Mode” on page 158 for more information about Non-multiplexed operation.

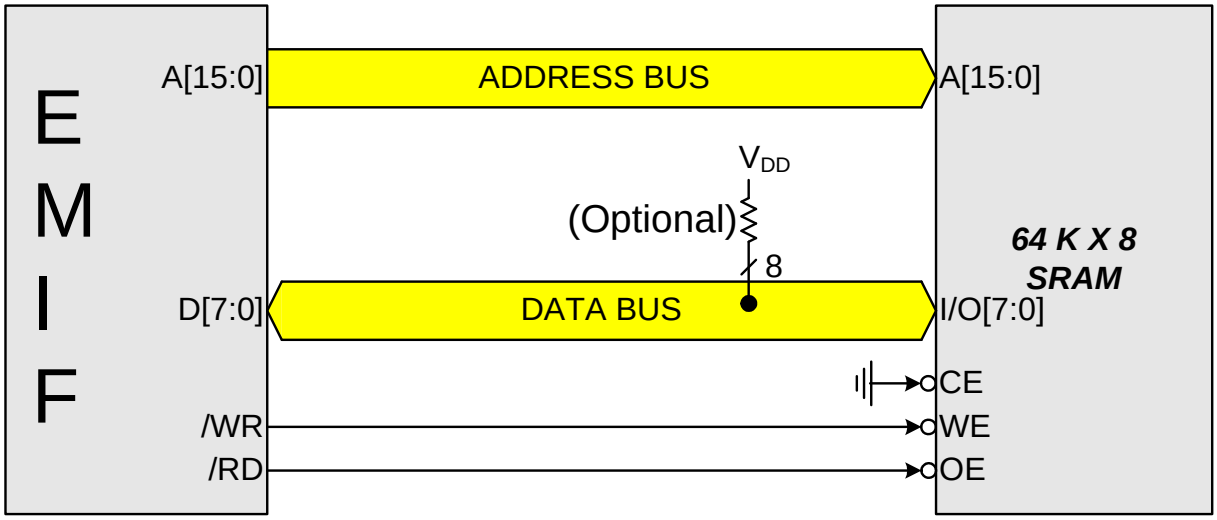


Figure 18.2. Non-multiplexed Configuration Example

19.2. Programmable Internal Oscillator

All C8051F50x/F51x devices include a programmable internal high-frequency oscillator that defaults as the system clock after a system reset. The internal oscillator period can be adjusted via the OSCICRS and OSCIFIN registers defined in SFR Definition 19.3 and SFR Definition 19.4. On C8051F50x/F51x devices, OSCICRS and OSCIFIN are factory calibrated to obtain a 24 MHz base frequency. Note that the system clock may be derived from the programmed internal oscillator divided by 1, 2, 4, 8, 16, 32, 64, or 128, as defined by the IFCN bits in register OSCICN. The divide value defaults to 128 following a reset.

19.2.1. Internal Oscillator Suspend Mode

When software writes a logic 1 to SUSPEND (OSCICN.5), the internal oscillator is suspended. If the system clock is derived from the internal oscillator, the input clock to the peripheral or CIP-51 will be stopped until one of the following events occur:

- Port 0 Match Event.
- Port 1 Match Event.
- Port 2 Match Event.
- Port 3 Match Event.
- Comparator 0 enabled and output is logic 0.

When one of the oscillator awakening events occur, the internal oscillator, CIP-51, and affected peripherals resume normal operation, regardless of whether the event also causes an interrupt. The CPU resumes execution at the instruction following the write to SUSPEND.

Note: When entering suspend mode, firmware must set the ZTCEN bit in REF0CN (SFR Definition 8.1).

19.3. Clock Multiplier

The Clock Multiplier generates an output clock which is 4 times the input clock frequency scaled by a programmable factor of 1, 2/3, 2/4 (or 1/2), 2/5, 2/6 (or 1/3), or 2/7. The Clock Multiplier's input can be selected from the external oscillator, or the internal or external oscillators divided by 2. This produces three possible base outputs which can be scaled by a programmable factor: Internal Oscillator x 2, External Oscillator x 2, or External Oscillator x 4. See Section 19.1 on page 165 for details on system clock selection.

The Clock Multiplier is configured via the CLKMUL register (SFR Definition 19.5). The procedure for configuring and enabling the Clock Multiplier is as follows:

1. Reset the Multiplier by writing 0x00 to register CLKMUL.
2. Select the Multiplier input source via the MULSEL bits.
3. Select the Multiplier output scaling factor via the MULDIV bits
4. Enable the Multiplier with the MULEN bit (CLKMUL | = 0x80).
5. Delay for >5 µs.
6. Initialize the Multiplier with the MULINIT bit (CLKMUL | = 0xC0).
7. Poll for MULRDY => 1.

Important Note: When using an external oscillator as the input to the Clock Multiplier, the external source must be enabled and stable before the Multiplier is initialized. See "19.4. External Oscillator Drive Circuit" on page 172 for details on selecting an external oscillator source.

The Clock Multiplier allows faster operation of the CIP-51 core and is intended to generate an output frequency between 25 and 50 MHz. The clock multiplier can also be used with slow input clocks. However, if the clock is below the minimum Clock Multiplier input frequency (FCM_{min}), the generated clock will consist of four fast pulses followed by a long delay until the next input clock rising edge. The average frequency of the output is equal to 4x the input, but the instantaneous frequency may be faster. See Figure 19.2 below for more information.

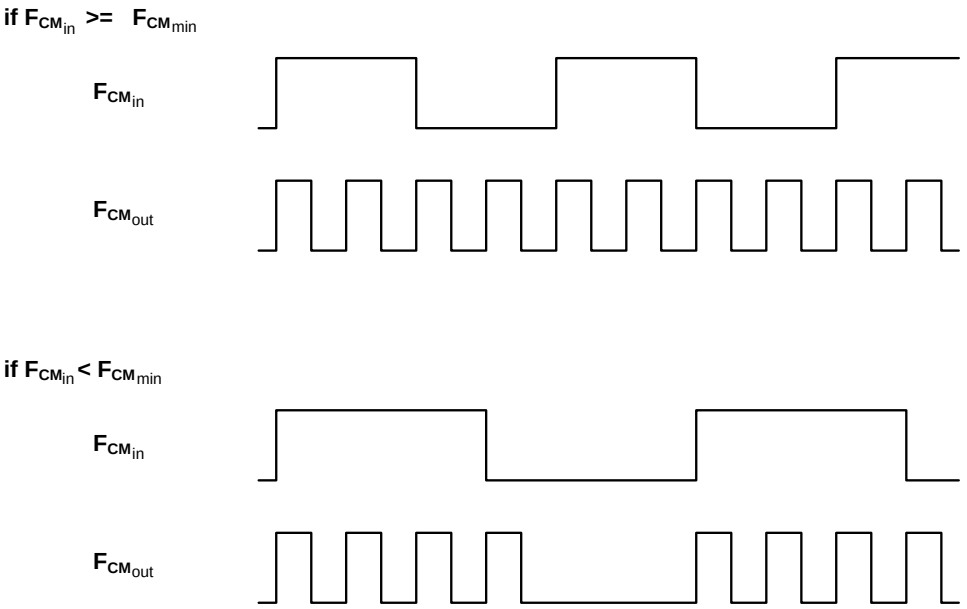


Figure 19.2. Example Clock Multiplier Output

20.1. Port I/O Modes of Operation

Port pins P0.0–P4.7 use the Port I/O cell shown in Figure 20.2. Each Port I/O cell can be configured by software for analog I/O or digital I/O using the PnMDIN registers. On reset, all Port I/O cells default to a high impedance state with weak pull-ups enabled until the Crossbar is enabled (XBARE = 1).

20.1.1. Port Pins Configured for Analog I/O

Any pins to be used as Comparator or ADC inputs, external oscillator inputs, or VREF should be configured for analog I/O (PnMDIN.n = 0). When a pin is configured for analog I/O, its weak pullup, digital driver, and digital receiver are disabled. Port pins configured for analog I/O will always read back a value of 0.

Configuring pins as analog I/O saves power and isolates the Port pin from digital interference. Port pins configured as digital inputs may still be used by analog peripherals; however, this practice is not recommended and may result in measurement errors.

20.1.2. Port Pins Configured For Digital I/O

Any pins to be used by digital peripherals (UART, SPI, SMBus, etc.), external digital event capture functions, or as GPIO should be configured as digital I/O (PnMDIN.n = 1). For digital I/O pins, one of two output modes (push-pull or open-drain) must be selected using the PnMDOUT registers.

Push-pull outputs (PnMDOUT.n = 1) drive the Port pad to the VIO or GND supply rails based on the output logic value of the Port pin. Open-drain outputs have the high side driver disabled; therefore, they only drive the Port pad to GND when the output logic value is 0 and become high impedance inputs (both high low drivers turned off) when the output logic value is 1.

When a digital I/O cell is placed in the high impedance state, a weak pull-up transistor pulls the Port pad to the VIO supply voltage to ensure the digital input is at a defined logic state. Weak pull-ups are disabled when the I/O cell is driven to GND to minimize power consumption and may be globally disabled by setting WEAKPUD to 1. The user should ensure that digital I/O are always internally or externally pulled or driven to a valid logic state to minimize power consumption. Port pins configured for digital I/O always read back the logic state of the Port pad, regardless of the output logic value of the Port pin.

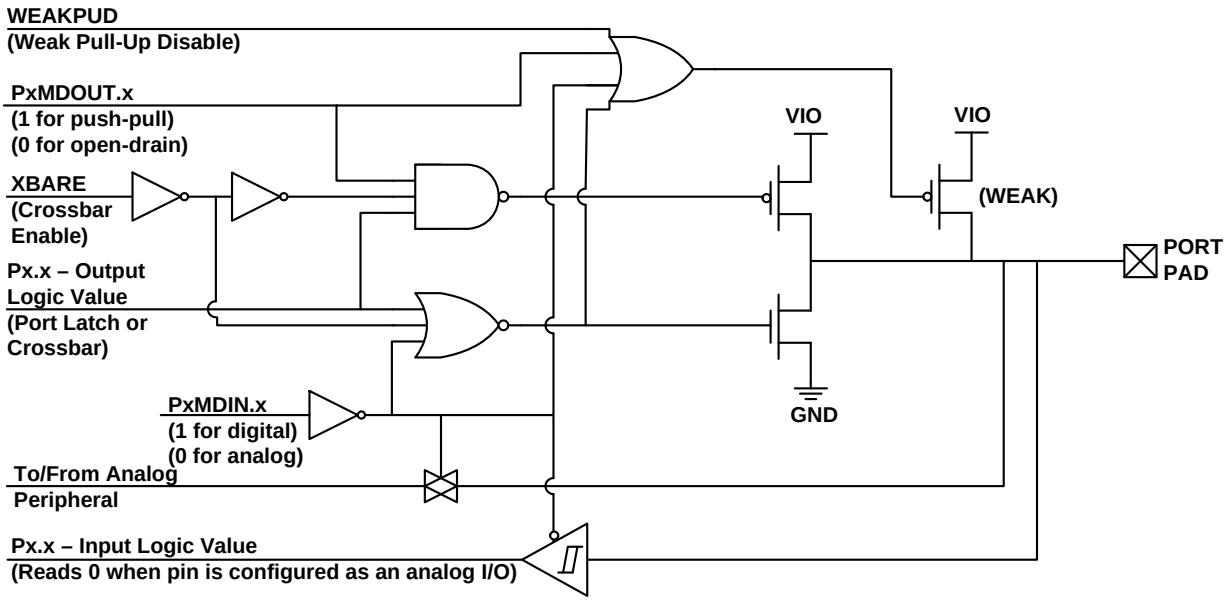


Figure 20.2. Port I/O Cell Block Diagram

SFR Definition 20.19. P1SKIP: Port 1 Skip

Bit	7	6	5	4	3	2	1	0
Name	P1SKIP[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Address = 0xD5; SFR Page = 0x0F

Bit	Name	Function
7:0	P1SKIP[7:0]	**Port 1 Crossbar Skip Enable Bits.** These bits select Port 1 pins to be skipped by the Crossbar Decoder. Port pins used for analog, special functions or GPIO should be skipped by the Crossbar. 0: Corresponding P1.n pin is not skipped by the Crossbar. 1: Corresponding P1.n pin is skipped by the Crossbar.

SFR Definition 20.20. P2: Port 2

Bit	7	6	5	4	3	2	1	0
Name	P2[7:0]							
Type	R/W							
Reset	1	1	1	1	1	1	1	1

SFR Address = 0xA0; SFR Page = All Pages; Bit-Addressable

Bit	Name	Description	Write	Read
7:0	P2[7:0]	**Port 2Data.** Sets the Port latch logic value or reads the Port pin logic state in Port cells configured for digital I/O.	0: Set output latch to logic LOW. 1: Set output latch to logic HIGH.	0: P2.n Port pin is logic LOW. 1: P2.n Port pin is logic HIGH.

LIN Register Definition 21.11. LIN0ID: LIN0 Identifier Register

Bit	7	6	5	4	3	2	1	0
Name			ID[5:0]					
Type	R	R	R/W					
Reset	0	0	0	0	0	0	0	0

Indirect Address = 0x0E

Bit	Name	Function
7:6	Unused	Read = 00b; Write = Don't Care.
5:0	ID[5:0]	**LIN Identifier Bits.** These bits form the data identifier. If the LINSIZE bits (LIN0SIZE[3:0]) are 1111b, bits ID[5:4] are used to determine the data size and are interpreted as follows: 00: 2 bytes 01: 2 bytes 10: 4 bytes 11: 8 bytes

24. UART0

UART0 is an asynchronous, full duplex serial port offering a variety of data formatting options. A dedicated baud rate generator with a 16-bit timer and selectable prescaler is included, which can generate a wide range of baud rates (details in Section “24.1. Baud Rate Generator” on page 243). A received data FIFO allows UART0 to receive up to three data bytes before data is lost and an overflow occurs.

UART0 has six associated SFRs. Three are used for the Baud Rate Generator (SBCON0, SBRLH0, and SBRLL0), two are used for data formatting, control, and status functions (SCON0, SMOD0), and one is used to send and receive data (SBUF0). The single SBUF0 location provides access to both transmit and receive registers. **Writes to SBUF0 always access the Transmit register. Reads of SBUF0 always access the buffered Receive register; it is not possible to read data from the Transmit register.**

With UART0 interrupts enabled, an interrupt is generated each time a transmit is completed (TI0 is set in SCON0), or a data byte has been received (RI0 is set in SCON0). The UART0 interrupt flags are not cleared by hardware when the CPU vectors to the interrupt service routine. They must be cleared manually by software, allowing software to determine the cause of the UART0 interrupt (transmit complete or receive complete). If additional bytes are available in the Receive FIFO, the RI0 bit cannot be cleared by software.

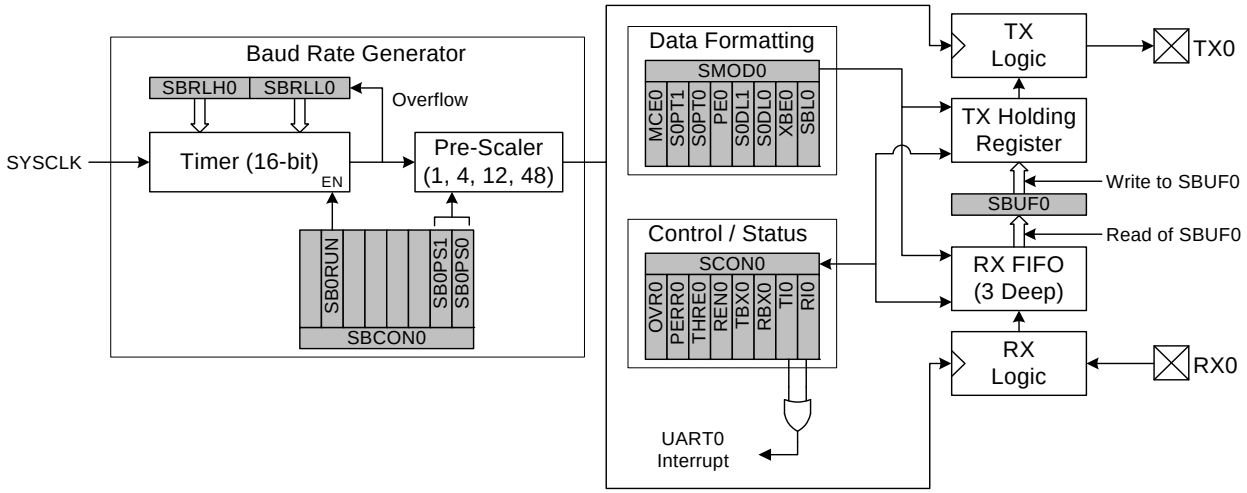
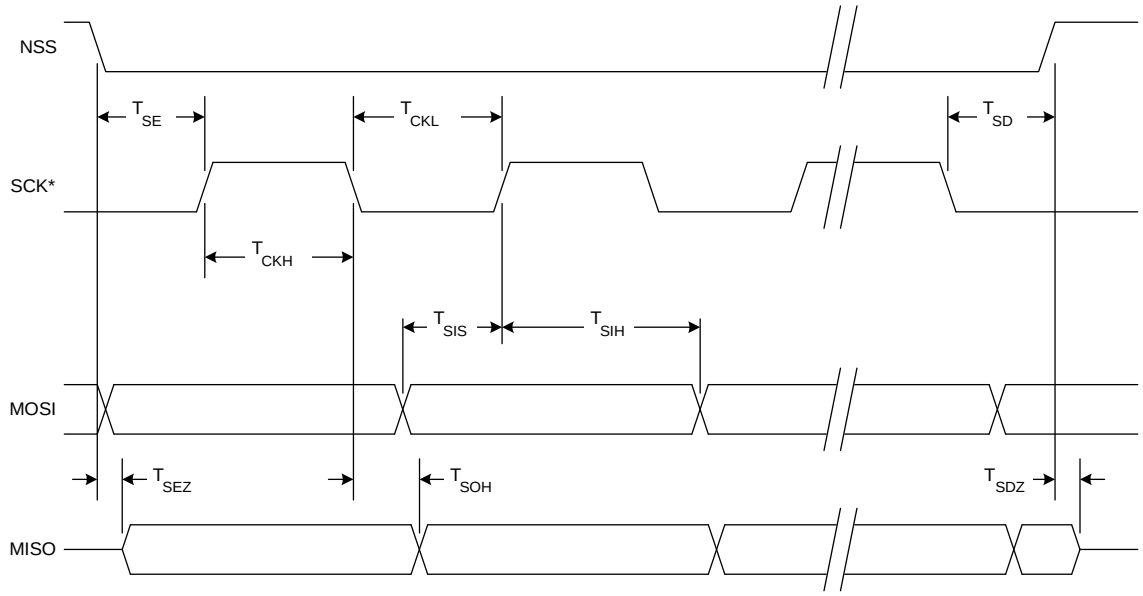


Figure 24.1. UART0 Block Diagram

24.1. Baud Rate Generator

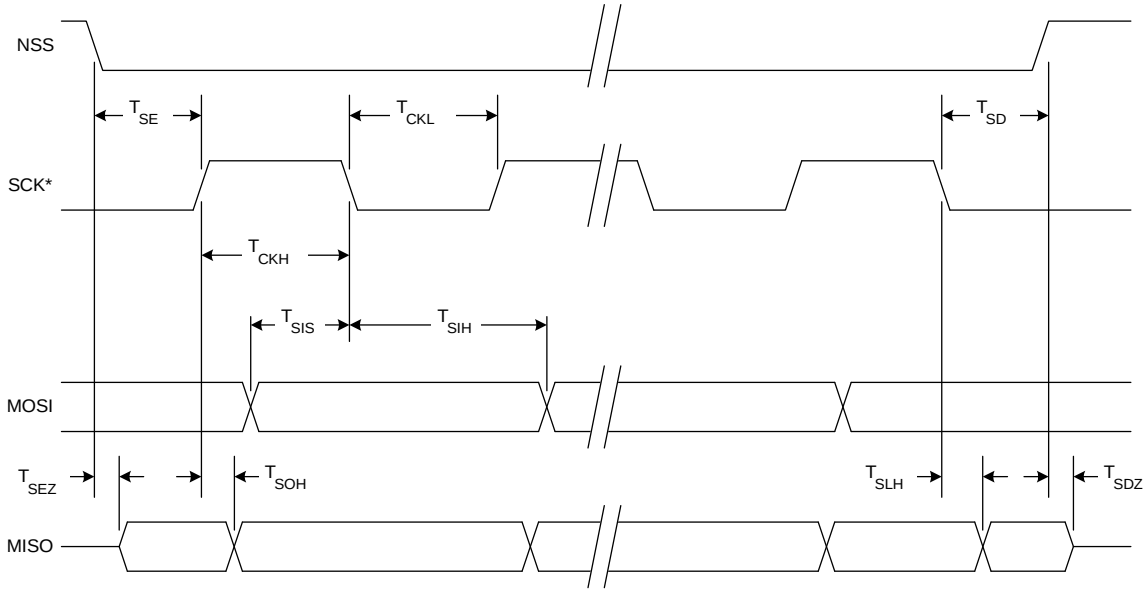
The UART0 baud rate is generated by a dedicated 16-bit timer which runs from the controller’s core clock (SYSCLK) and has prescaler options of 1, 4, 12, or 48. The timer and prescaler options combined allow for a wide selection of baud rates over many clock frequencies.

The baud rate generator is configured using three registers: SBCON0, SBRLH0, and SBRLL0. The UART0 Baud Rate Generator Control Register (SBCON0, SFR Definition 24.4) enables or disables the baud rate generator, selects the clock source for the baud rate generator, and selects the prescaler value for the timer. The baud rate generator must be enabled for UART0 to function. Registers SBRLH0 and SBRLL0 contain a 16-bit reload value for the dedicated 16-bit timer. The internal timer counts up from the reload value on every clock tick. On timer overflows (0xFFFF to 0x0000), the timer is reloaded. The baud rate for UART0 is defined in Equation 24.1, where “BRG Clock” is the baud rate generator’s selected clock source. For reliable UART operation, it is recommended that the UART baud rate is not configured for baud rates faster than SYSCLK/16.



* SCK is shown for CKPOL = 0. SCK is the opposite polarity for CKPOL = 1.

Figure 25.10. SPI Slave Timing (CKPHA = 0)



* SCK is shown for CKPOL = 0. SCK is the opposite polarity for CKPOL = 1.

Figure 25.11. SPI Slave Timing (CKPHA = 1)

SFR Definition 26.1. CKCON: Clock Control

Bit	7	6	5	4	3	2	1	0
Name	T3MH	T3ML	T2MH	T2ML	T1M	T0M	SCA[1:0]	
Type	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Reset	0	0	0	0	0	0	0	0

SFR Address = 0x8E; SFR Page = All Pages

Bit	Name	Function
7	T3MH	**Timer 3 High Byte Clock Select.** Selects the clock supplied to the Timer 3 high byte (split 8-bit timer mode only). 0: Timer 3 high byte uses the clock defined by the T3XCLK bit in TMR3CN. 1: Timer 3 high byte uses the system clock.
6	T3ML	**Timer 3 Low Byte Clock Select.** Selects the clock supplied to Timer 3. Selects the clock supplied to the lower 8-bit timer in split 8-bit timer mode. 0: Timer 3 low byte uses the clock defined by the T3XCLK bit in TMR3CN. 1: Timer 3 low byte uses the system clock.
5	T2MH	**Timer 2 High Byte Clock Select.** Selects the clock supplied to the Timer 2 high byte (split 8-bit timer mode only). 0: Timer 2 high byte uses the clock defined by the T2XCLK bit in TMR2CN. 1: Timer 2 high byte uses the system clock.
4	T2ML	**Timer 2 Low Byte Clock Select.** Selects the clock supplied to Timer 2. If Timer 2 is configured in split 8-bit timer mode, this bit selects the clock supplied to the lower 8-bit timer. 0: Timer 2 low byte uses the clock defined by the T2XCLK bit in TMR2CN. 1: Timer 2 low byte uses the system clock.
3	T1	**Timer 1 Clock Select.** Selects the clock source supplied to Timer 1. Ignored when C/T1 is set to 1. 0: Timer 1 uses the clock defined by the prescale bits SCA[1:0]. 1: Timer 1 uses the system clock.
2	T0	**Timer 0 Clock Select.** Selects the clock source supplied to Timer 0. Ignored when C/T0 is set to 1. 0: Counter/Timer 0 uses the clock defined by the prescale bits SCA[1:0]. 1: Counter/Timer 0 uses the system clock.
1:0	SCA[1:0]	**Timer 0/1 Prescale Bits.** These bits control the Timer 0/1 Clock Prescaler: 00: System clock divided by 12 01: System clock divided by 4 10: System clock divided by 48 11: External clock divided by 8 (synchronized with the system clock)

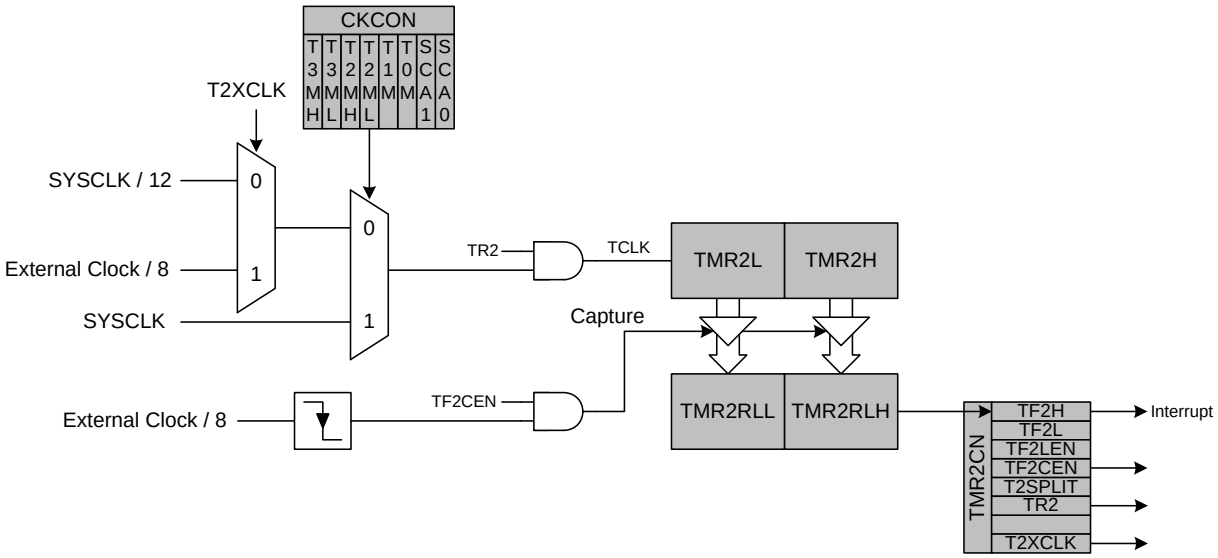


Figure 26.6. Timer 2 External Oscillator Capture Mode Block Diagram

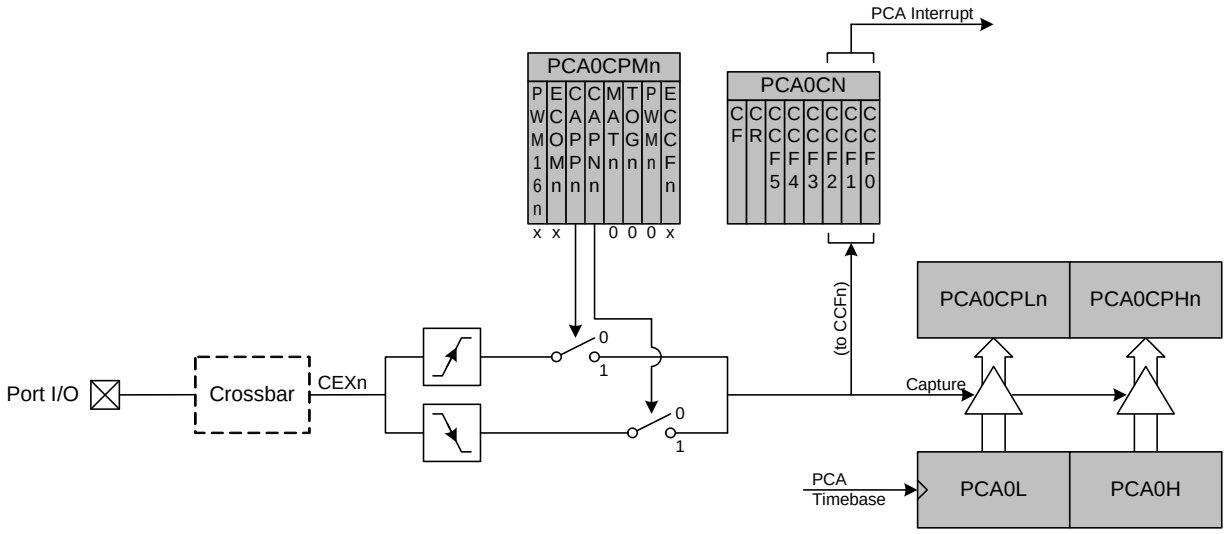


Figure 27.4. PCA Capture Mode Diagram

Note: The CEXn input signal must remain high or low for at least 2 system clock cycles to be recognized by the hardware.

27.3.2. Software Timer (Compare) Mode

In Software Timer mode, the PCA counter/timer value is compared to the module's 16-bit capture/compare register (PCA0CPHn and PCA0CPLn). When a match occurs, the Capture/Compare Flag (CCFn) in PCA0CN is set to logic 1. An interrupt request is generated if the CCFn interrupt for that module is enabled. The CCFn bit is not automatically cleared by hardware when the CPU vectors to the interrupt service routine, and must be cleared by software. Setting the ECOMn and MATn bits in the PCA0CPMn register enables Software Timer mode.

Important Note About Capture/Compare Registers: When writing a 16-bit value to the PCA0 Capture/Compare registers, the low byte should always be written first. Writing to PCA0CPLn clears the ECOMn bit to 0; writing to PCA0CPHn sets ECOMn to 1.

28. C2 Interface

C8051F50x/F51x devices include an on-chip Silicon Labs 2-Wire (C2) debug interface to allow Flash programming and in-system debugging with the production part installed in the end application. The C2 interface uses a clock signal (C2CK) and a bi-directional C2 data signal (C2D) to transfer information between the device and a host system. See the C2 Interface Specification for details on the C2 protocol.

28.1. C2 Interface Registers

The following describes the C2 registers necessary to perform Flash programming through the C2 interface. All C2 registers are accessed through the C2 interface as described in the C2 Interface Specification.

C2 Register Definition 28.1. C2ADD: C2 Address

Bit	7	6	5	4	3	2	1	0
Name	C2ADD[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

Bit	Name	Function	
7:0	C2ADD[7:0]	**C2 Address.** The C2ADD register is accessed via the C2 interface to select the target Data register for C2 Data Read and Data Write commands.	
		Address	**Description**
		0x00	Selects the Device ID register for Data Read instructions
		0x01	Selects the Revision ID register for Data Read instructions
		0x02	Selects the C2 Flash Programming Control register for Data Read/Write instructions
		0xB4	Selects the C2 Flash Programming Data register for Data Read/Write instructions